

# SI-3000KS Series Surface-Mount, Low Current Consumption, Low Dropout Voltage Linear Regulator ICs

## Features

- Compact surface-mount package (SOP8)
- Output current: 1.0 A
- Compatible with low ESR capacitor
- Low circuit current at output OFF  $I_q \leq 350 \mu\text{A}$  ( $I_o = 0 \text{ A}$ ,  $V_c = 2 \text{ V}$ )
- Low current consumption  $I_q (\text{OFF}) \leq 1 \mu\text{A}$  ( $V_c = 0 \text{ V}$ )
- Low dropout voltage  $V_{\text{DIF}} \leq 0.6 \text{ V}$  ( $I_o = 1 \text{ A}$ )
- 3 types of output voltages (2.5 V, 3.3 V, and variable type) available
- Output ON/OFF control terminal voltage compatible with LS-TTL
- Built-in drooping-type-overcurrent and thermal protection circuits

## Absolute Maximum Ratings

( $T_a=25^\circ\text{C}$ )

Parameter	Symbol	Ratings	Unit
DC Input Voltage	$V_{\text{IN}}^{*1}$	17	V
Output Control Terminal Voltage	$V_c$	$V_{\text{IN}}$	V
DC Output Current	$I_o^{*1}$	1.0	A
Power Dissipation	$P_D^{*1, *2}$	0.76	W
Junction Temperature	$T_j$	-40 to +125	$^\circ\text{C}$
Storage Temperature	$T_{\text{stg}}$	-40 to +125	$^\circ\text{C}$
Thermal Resistance (Junction to Ambient Air)	$\theta_{\text{JA}}^*$	130	$^\circ\text{C/W}$
Thermal resistance (Junction to Lead (pin 7))	$\theta_{\text{JL}}$	22	$^\circ\text{C/W}$

\*1:  $V_{\text{IN}}$  (max) and  $I_o$  (max) are restricted by the relation  $P_D = (V_{\text{IN}} - V_o) \times I_o$ . Please calculate these values referring to the Copper laminate area vs. Power dissipation data as shown hereinafter.

\*2: When mounted on a glass epoxy board of 1600 mm<sup>2</sup> (copper laminate area 2%).

## Applications

- Local power supplies
- Battery-driven electronic equipment

## Electrical Characteristics

( $T_a=25^\circ\text{C}$ ,  $V_c=2 \text{ V}$  unless otherwise specified)

Parameter	Symbol	Ratings									Unit
		SI-3012KS (variable type)			SI-3025KS			SI-3033KS			
		min.	typ.	max.	min.	typ.	max.	min.	typ.	max.	
Input Voltage	$V_{\text{IN}}$	2.4			*1			*1			V
Output Voltage (Reference voltage $V_{\text{ADJ}}$ for SI-3012KS)	$V_o (V_{\text{ADJ}})$	1.24	1.28	1.32	2.45	2.50	2.55	3.234	3.300	3.366	V
Dropout Voltage	$V_{\text{DIF}}$			0.3			0.4			0.4	V
	Conditions	$V_{\text{IN}}=3.3\text{V}$ , $I_o=10\text{mA}$			$V_{\text{IN}}=3.3\text{V}$ , $I_o=10\text{mA}$			$V_{\text{IN}}=5\text{V}$ , $I_o=10\text{mA}$			
	Conditions	$I_o=0.5\text{A}$ ( $V_c=2.5\text{V}$ )			$I_o=0.5\text{A}$			$I_o=0.5\text{A}$			
Line Regulation	$\Delta V_{\text{OLINE}}$			10			10			15	mV
	Conditions	$V_{\text{IN}}=3.3$ to $8\text{V}$ , $I_o=10\text{mA}$ ( $V_c=2.5\text{V}$ )			$V_{\text{IN}}=3.3$ to $8\text{V}$ , $I_o=10\text{mA}$			$V_{\text{IN}}=5$ to $10\text{V}$ , $I_o=10\text{mA}$			
Load Regulation	$\Delta V_{\text{OLOAD}}$			40			40			50	mV
	Conditions	$V_{\text{IN}}=3.3\text{V}$ , $I_o=0$ to $1\text{A}$ ( $V_c=2.5\text{V}$ )			$V_{\text{IN}}=3.3\text{V}$ , $I_o=0$ to $1\text{A}$			$V_{\text{IN}}=5\text{V}$ , $I_o=0$ to $1\text{A}$			
Quiescent Circuit Current	$I_q$			350			350			350	$\mu\text{A}$
	Conditions	$V_{\text{IN}}=3.3\text{V}$ , $I_o=0\text{A}$ , $V_c=2\text{V}$ , $R_2=24\text{k}\Omega$			$V_{\text{IN}}=3.3\text{V}$ , $I_o=0\text{A}$ , $V_c=2\text{V}$			$V_{\text{IN}}=5\text{V}$ , $I_o=0\text{A}$ , $V_c=2\text{V}$			
Circuit Current at Output OFF	$I_q (\text{OFF})$			1			1			1	$\mu\text{A}$
	Conditions	$V_{\text{IN}}=3.3\text{V}$ , $V_c=0\text{V}$			$V_{\text{IN}}=3.3\text{V}$ , $V_c=0\text{V}$			$V_{\text{IN}}=5\text{V}$ , $V_c=0\text{V}$			
Temperature Coefficient of Output Voltage	$\Delta V_o/\Delta T_a$		$\pm 0.3$			$\pm 0.3$			$\pm 0.3$		mV/ $^\circ\text{C}$
	Conditions	$T_j=0$ to $100^\circ\text{C}$ ( $V_o=2.5\text{V}$ )			$T_j=0$ to $100^\circ\text{C}$			$T_j=0$ to $100^\circ\text{C}$			
Ripple Rejection	$R_{\text{REJ}}$		55			55			55		dB
	Conditions	$V_{\text{IN}}=3.3\text{V}$ , $f=100$ to $120\text{Hz}$ ( $V_c=2.5\text{V}$ )			$V_{\text{IN}}=3.3\text{V}$ , $f=100$ to $120\text{Hz}$			$V_{\text{IN}}=5\text{V}$ , $f=100$ to $120\text{Hz}$			
Overcurrent Protection Starting Current*2	$I_{\text{S1}}$	1.2			1.2			1.2			A
	Conditions	$V_{\text{IN}}=3.3\text{V}$ ( $V_c=2.5\text{V}$ )			$V_{\text{IN}}=3.3\text{V}$			$V_{\text{IN}}=5\text{V}$			
$V_c$ Terminal	Control Voltage (Output ON)*3	$V_c, \text{IH}$	2.0		2.0			2.0			V
	Control Voltage (Output OFF)	$V_c, \text{IL}$			0.8		0.8			0.8	
	Control Current (Output ON)	$I_c, \text{IH}$			40		40			40	$\mu\text{A}$
	Conditions	$V_c=2\text{V}$									
	Control Current (Output OFF)	$I_c, \text{IL}$	-5	0		-5	0		-5	0	
Conditions	$V_c=0\text{V}$										

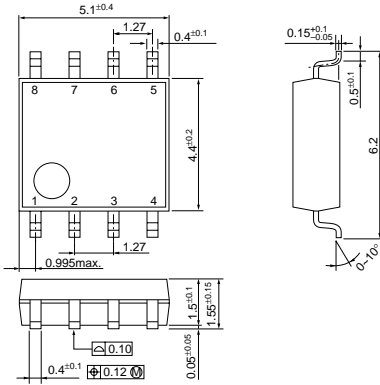
\*1: Refer to the Dropout Voltage parameter.

\*2: The  $I_{\text{S1}}$  is specified at the 5% drop point of output voltage  $V_o$  on the condition that  $V_{\text{IN}} = V_o + 1 \text{ V}$ , and  $I_o = 10 \text{ mA}$ .

\*3: Output is OFF when the output control terminal  $V_c$  is open. Each input level is equivalent to LS-TTL level. Therefore, the device can be driven directly by LS-TTLs.

External Dimensions (SOP8)

(Unit : mm)

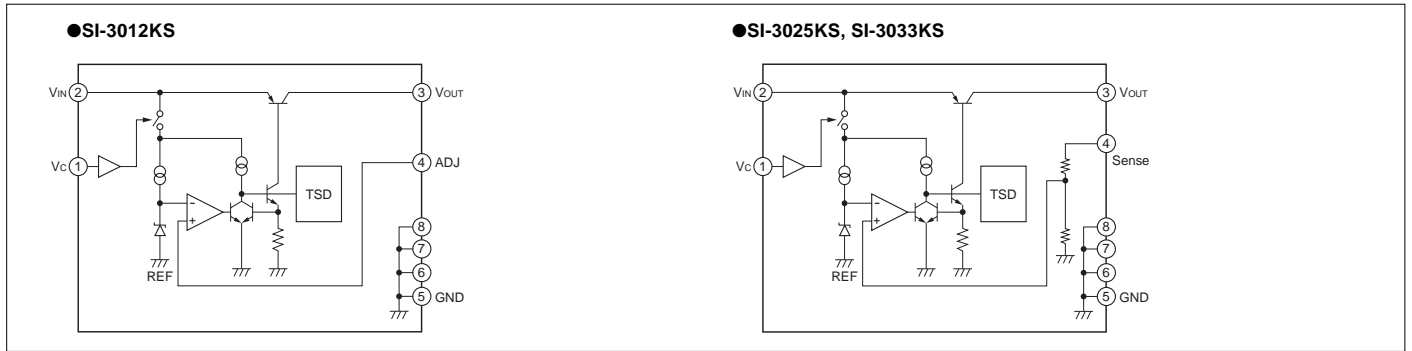


Pin Assignment

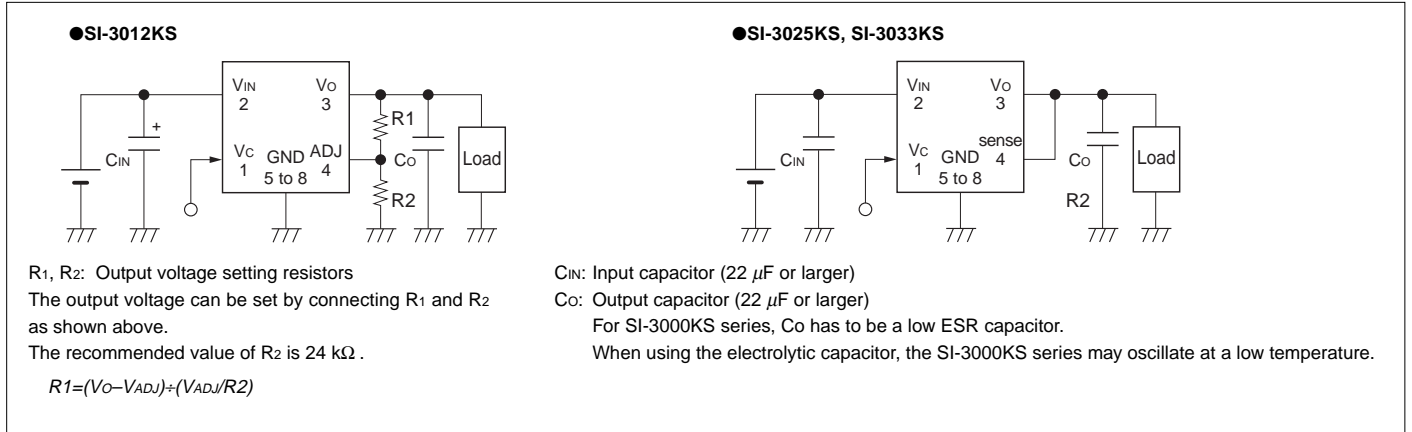
- ① Vc
- ② VIN
- ③ Vo
- ④ Sence (ADJ for SI-3012KS)
- ⑤ GND
- ⑥ GND
- ⑦ GND
- ⑧ GND

Plastic Mold Package Type  
 Flammability: UL 94V-0  
 Product Mass: Approx. 0.1 g

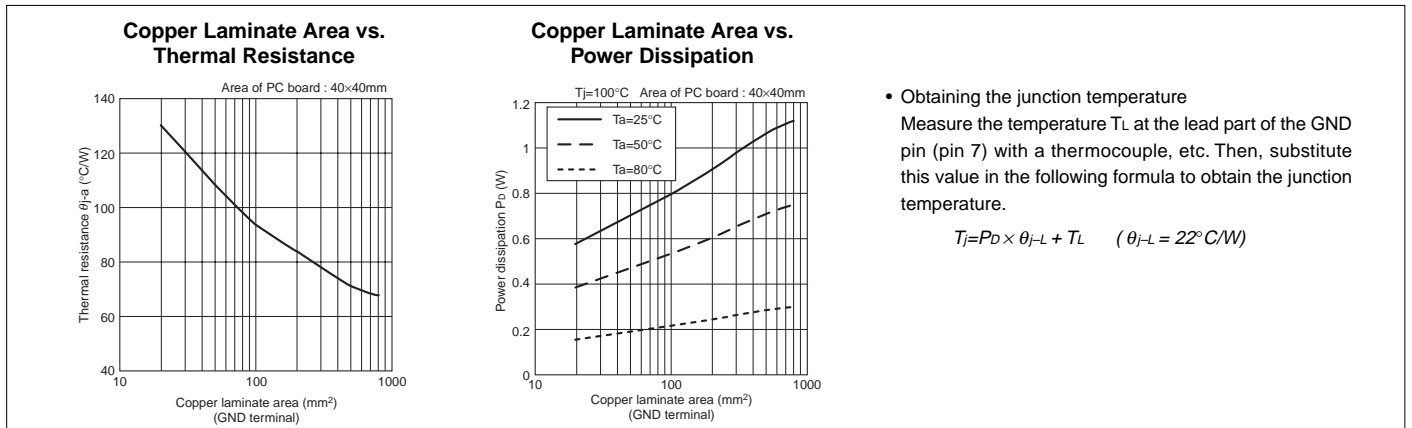
Block Diagram



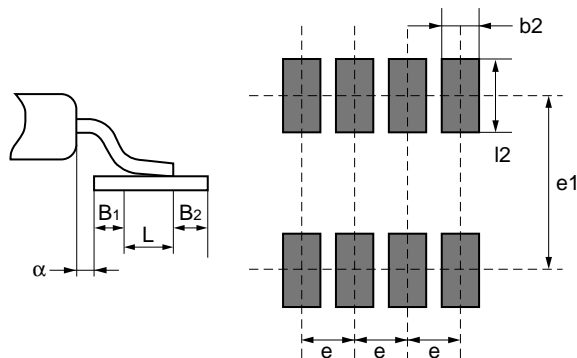
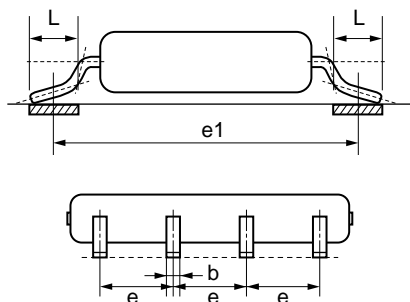
Typical Connection Diagram



Reference Data



■Example of Solder Pattern Design



Symbol	Dimensions (mm)
e1	5.72
e	1.27±0.15
α	0.2
β1	0.2 to 0.5
β2	0.2
L	0.6
b2	0.76
l2	L+β1+β2

(Reference value conforming to EIAJ Standard ED-7402-1)

\*1 The inner frame stage on which a monolithic IC is mounted is directly connected to the GND pins (pins 5 through 8). By expanding the area of the copper connected to the GND pins, the heat radiation can be improved. It is recommended to design the solder pattern by opening the insulation film of the solder patterns of pins 5, 6, 7, and 8, on the wide GND pattern as shown in Figure 1.

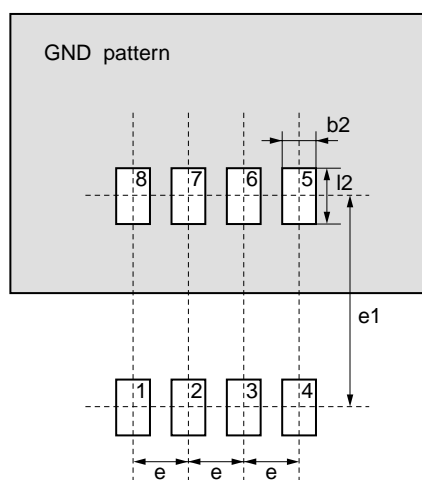
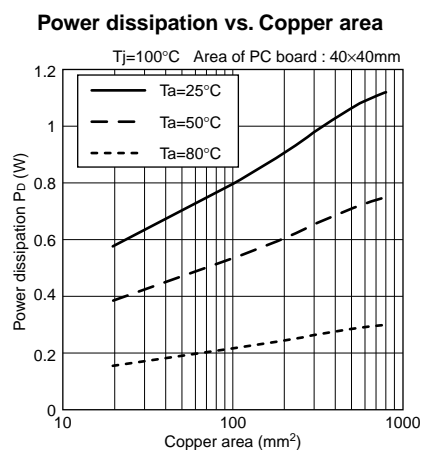
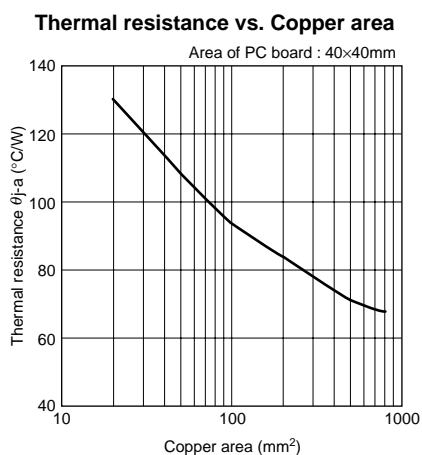


Figure 1

■Reference Data



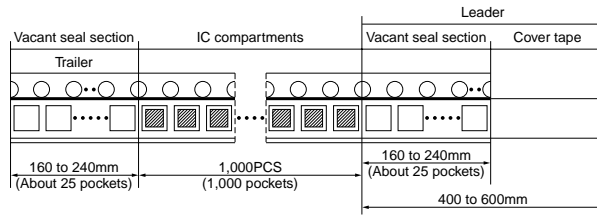
- Calculating junction temperature  
Measure the temperature TL of the lead of the GND pin (pin 7) by using a thermocouple, and substitute the measured value into the following expression to calculate the junction temperature.

$$T_j = P_D \times \theta_{j-L} + T_L \quad (\theta_{j-L} = 22^\circ \text{C/W})$$

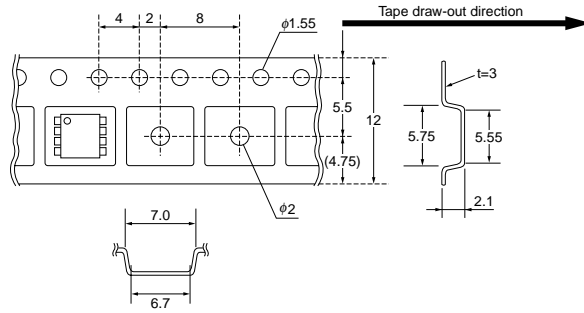
### ■Taping Specifications

#### Carrier tape

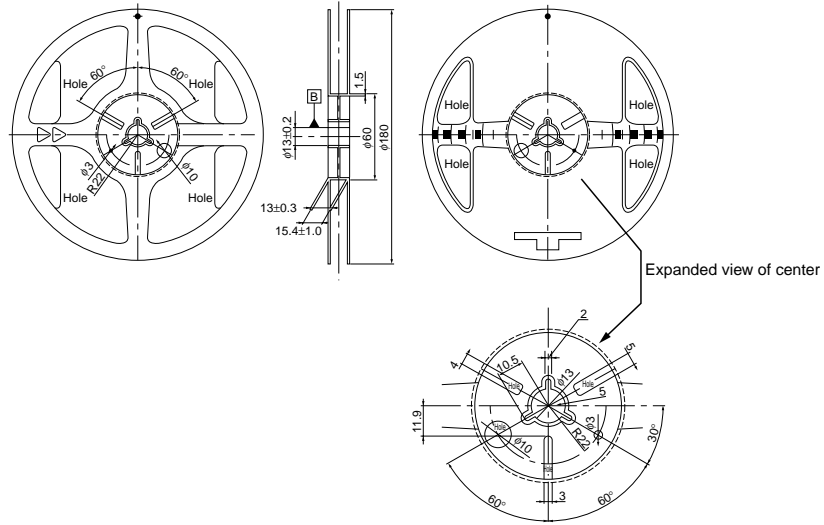
Surface resistance of embossed tape: 100 k $\Omega$  maximum (among 10 pockets)



(Unit : mm)



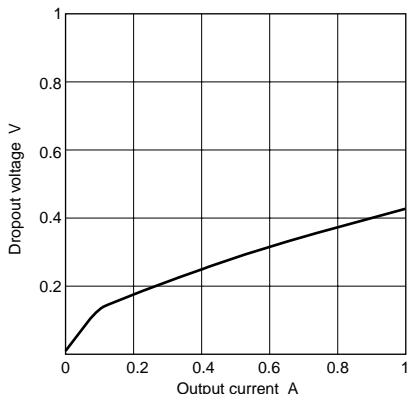
Reel: Number of packed products: 1000



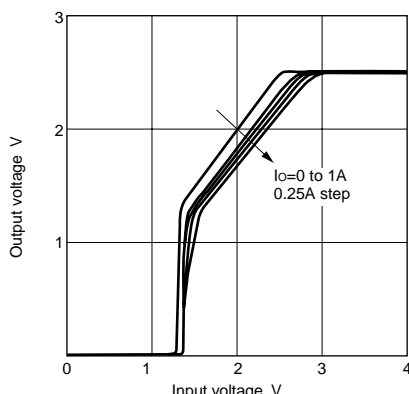
■Typical Characteristics Examples of SI-3012KS and SI-3025KS

( $T_a=25^\circ\text{C}$ ) \* $V_{out}=2.5\text{ V}$  for SI-3012KS ( $R_S=24\text{ k}\Omega$ )

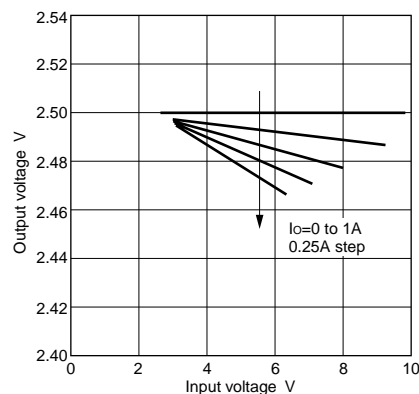
Dropout voltage



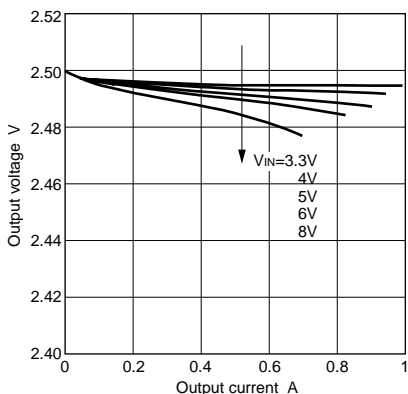
Rise characteristics



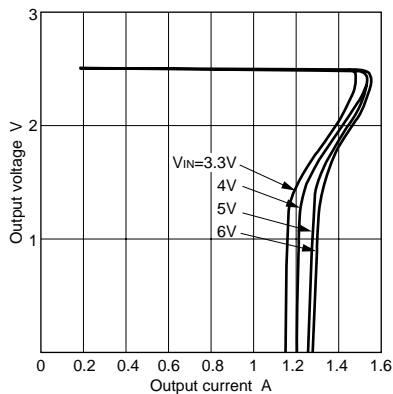
Line regulation



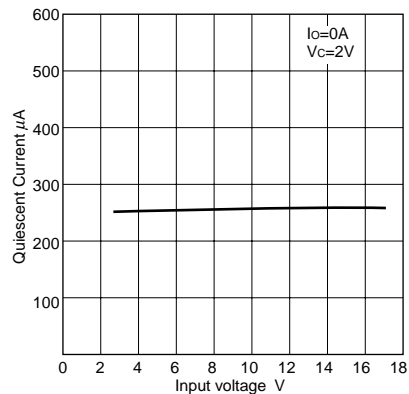
Load regulation



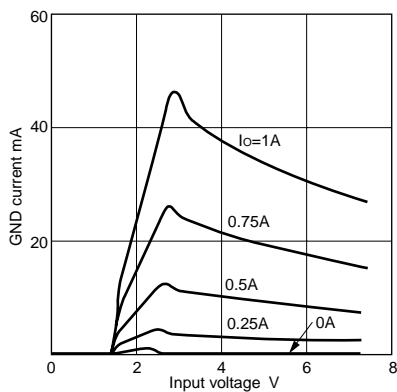
Overcurrent protection characteristics



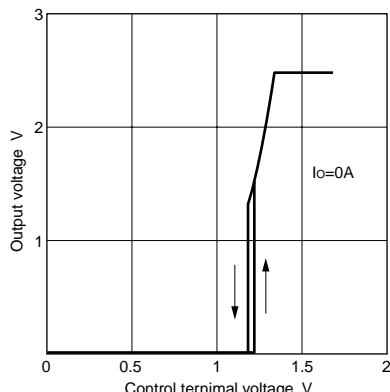
Input voltage vs. Quiescent current



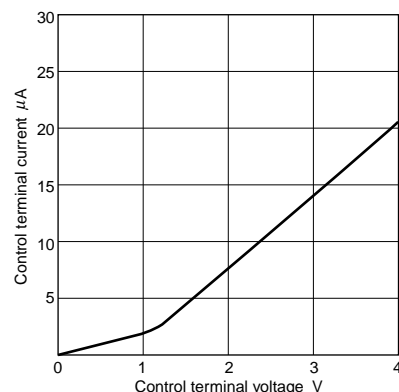
Circuit current



Control terminal voltage vs. Output voltage



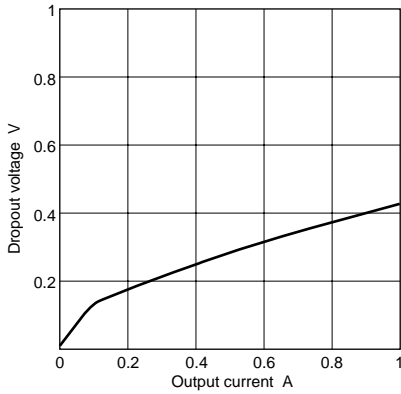
Control terminal voltage vs. Control terminal current



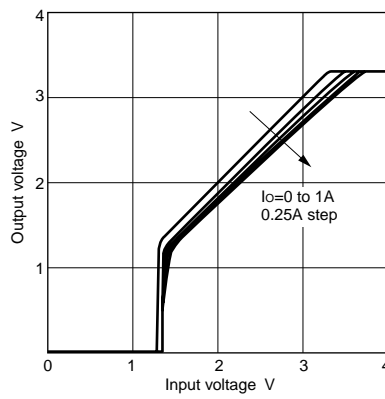
■Typical Characteristics Examples of SI-3033KS

( $T_a=25^\circ\text{C}$ )

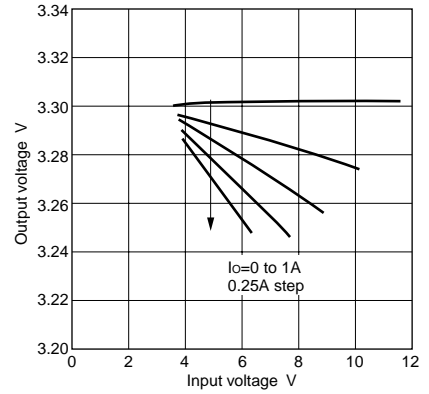
Dropout voltage



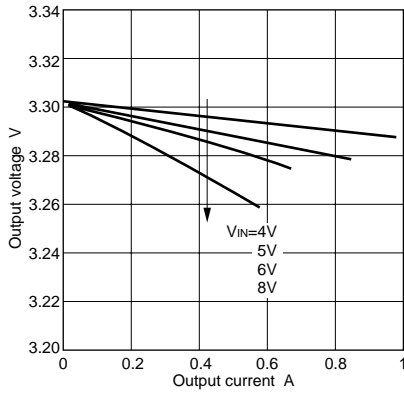
Rise characteristics



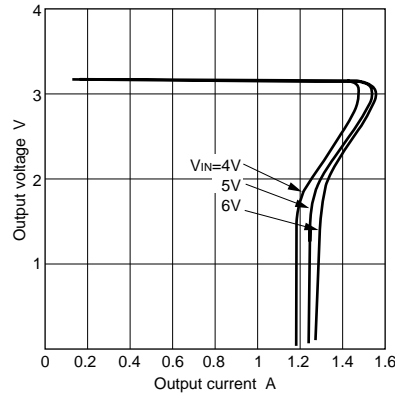
Line regulation



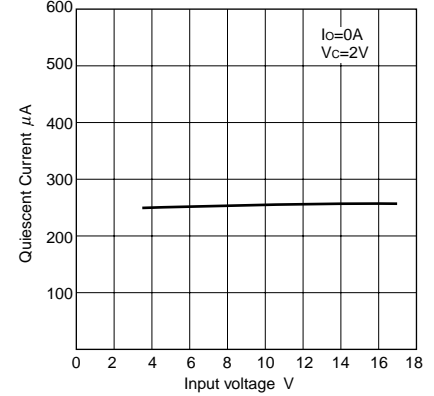
Load regulation



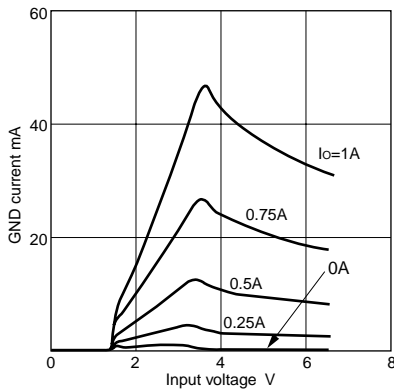
Overcurrent protection characteristics



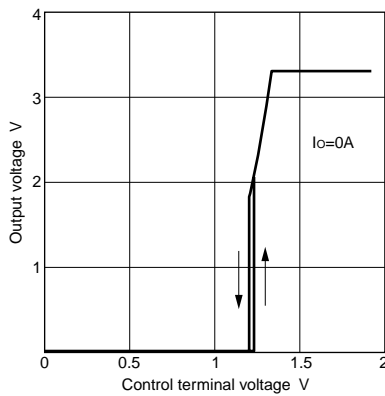
Input voltage vs. Quiescent current



Circuit current



Control terminal voltage vs. Output voltage



Control terminal voltage vs. Control terminal current

